# Memory Stick™ Duo Connectors CIM-G24 Series

Connectors

## OUTLINE

- 1. SMT-type connector for Memory Stick Duo.
- 2. Equipped with push-in, push-out eject mechanism.
- 3. Ideal for portable devices! Ultra-thin type, only 2.3mm high.
- 4. Space-saving, with width of 23.5mm and length of 27.8mm (not including leads).
- 5. Equipped with half lock to prevent card from falling out, and full lock mechanism when coupled.

<sup>\*</sup>Memory  $\mathsf{Stick}^\mathsf{TM}$  is a registered trademark of SONY Corporation.



### **HOW TO ORDER**

# $\frac{G24}{1} - \frac{O10}{2} - \frac{21}{3} \quad \frac{O}{4} - \frac{A}{5} \quad \frac{G}{6} \quad \frac{G}{7} \quad \frac{E}{8}$

1. Series No. (G24)

2. No. of contacts (010 : 10pins)

3. Housing material (21: LCP resin)

4. UL grade (0: UL94-V0)5. Contact plating (A: Gold)

6. Contact plating thickness (G: 0.3µm)

7. Contact style (G: Angle) 8. Package (E: Taping)

# SPECIFICATIONS

#### **ELECTRICAL CHARACTERISTICS**

Rated Voltage	AC 50V (rms)	
Rated Current	0.5A	
Withstanding Voltage	500V AC (rms) 1minute	
Insulation Resistance	1000MΩ min. (Initial 500V DC)	
Contact Resistance	40mΩ max.	

#### MECHANICAL CHARACTERISTICS

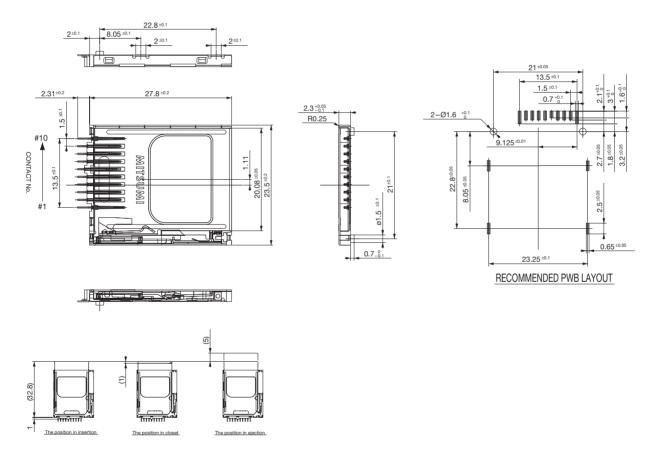
Life (Matching Cycle)	12,000 times	
Card Insertion Force	4.90N (0.5kgf)~8.83N (0.9kgf)	
Eject Force	4.90N (0.5kgf)~8.83N (0.9kgf)	
Using Temperature Range	−25~+60°C max. 95%	

# MATERIAL & FINISH

Component Parts	Material	Finish
Housing	LCP resin	(Black)
Contact	Copper Alloy	Gold plating
Plate	Copper Alloy	-
Half Lock	SUS	-
Slider	PA9T resin	(Black)
Coil Spring	SUS	-
Lock Pin	SUS	-
Lock Spring	SUS	-
Shaft	SUS	-

# DIMENSIONS

#### CIM-G24 Series



Unit: mm